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What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Details	
Product Status	Active
Core Processor	PIC
Core Size	8-Bit
Speed	4MHz
Connectivity	-
Peripherals	POR, WDT
Number of I/O	20
Program Memory Size	768B (512 x 12)
Program Memory Type	OTP
EEPROM Size	
RAM Size	25 x 8
Voltage - Supply (Vcc/Vdd)	2.5V ~ 5.5V
Data Converters	-
Oscillator Type	External
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Through Hole
Package / Case	28-DIP (0.300", 7.62mm)
Supplier Device Package	28-SPDIP
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic16lc55a-04i-sp

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

NOTES:

PIC16C5X

XORLW	Exclusive OR literal with W								
Syntax:	[label]	XORLW	k						
Operands:	$0 \le k \le 2$	55							
Operation:	(W) .XOF	$R. k \to (W$	/)						
Status Affected:	Z								
Encoding:	1111	kkkk	kkkk						
Description:	XOR'ed	with the e	e W regis eight bit lit ed in the V	eral 'k'.					
Words:	1								
Cycles:	1								
Example:	XORLW	0xAF							
Before Instru W = After Instruct W =	0xB5								

XORWF Exclusive OR W with f									
[label] XORWF f,d	-								
$\begin{array}{l} 0\leq f\leq 31\\ d\in [0,1] \end{array}$									
(W) .XOR. (f) \rightarrow (dest)									
ted: Z									
0001 10df ffff									
W register with register 'f'. If 'd' is 0 the result is stored in the W regis- ter. If 'd' is 1 the result is stored back in register 'f'.									
1									
1									
XORWF REG,1									
Instruction G = 0xAF = 0xB5 struction G = 0x1A = 0xB5									
the result is stored in t ter. If 'd' is 1 the result back in register 'f'. 1 1 XORWF REG, 1 nstruction G = 0xAF = 0xB5 struction	er 'f'. If 'd' is 0 the W regis-								

11.8 MPLAB ICD In-Circuit Debugger

Microchip's In-Circuit Debugger, MPLAB ICD, is a powerful, low cost, run-time development tool. This tool is based on the FLASH PIC MCUs and can be used to develop for this and other PIC microcontrollers. The MPLAB ICD utilizes the in-circuit debugging capability built into the FLASH devices. This feature, along with Microchip's In-Circuit Serial ProgrammingTM protocol, offers cost-effective in-circuit FLASH debugging from the graphical user interface of the MPLAB Integrated Development Environment. This enables a designer to develop and debug source code by watching variables, single-stepping and setting break points. Running at full speed enables testing hardware in real-time.

11.9 PRO MATE II Universal Device Programmer

The PRO MATE II universal device programmer is a full-featured programmer, capable of operating in Stand-alone mode, as well as PC-hosted mode. The PRO MATE II device programmer is CE compliant.

The PRO MATE II device programmer has programmable VDD and VPP supplies, which allow it to verify programmed memory at VDD min and VDD max for maximum reliability. It has an LCD display for instructions and error messages, keys to enter commands and a modular detachable socket assembly to support various package types. In Stand-alone mode, the PRO MATE II device programmer can read, verify, or program PIC devices. It can also set code protection in this mode.

11.10 PICSTART Plus Entry Level Development Programmer

The PICSTART Plus development programmer is an easy-to-use, low cost, prototype programmer. It connects to the PC via a COM (RS-232) port. MPLAB Integrated Development Environment software makes using the programmer simple and efficient.

The PICSTART Plus development programmer supports all PIC devices with up to 40 pins. Larger pin count devices, such as the PIC16C92X and PIC17C76X, may be supported with an adapter socket. The PICSTART Plus development programmer is CE compliant.

11.11 PICDEM 1 Low Cost PIC MCU Demonstration Board

The PICDEM 1 demonstration board is a simple board which demonstrates the capabilities of several of Microchip's microcontrollers. The microcontrollers supported are: PIC16C5X (PIC16C54 to PIC16C58A). PIC16C61, PIC16C62X, PIC16C71, PIC16C8X, PIC17C42, PIC17C43 and PIC17C44. All necessary hardware and software is included to run basic demo programs. The user can program the sample microcontrollers provided with the PICDEM 1 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The user can also connect the PICDEM 1 demonstration board to the MPLAB ICE incircuit emulator and download the firmware to the emulator for testing. A prototype area is available for the user to build some additional hardware and connect it to the microcontroller socket(s). Some of the features include an RS-232 interface, a potentiometer for simulated analog input, push button switches and eight LEDs connected to PORTB.

11.12 PICDEM 2 Low Cost PIC16CXX Demonstration Board

The PICDEM 2 demonstration board is a simple demonstration board that supports the PIC16C62, PIC16C64, PIC16C65, PIC16C73 and PIC16C74 microcontrollers. All the necessary hardware and software is included to run the basic demonstration programs. The user can program the sample microcontrollers provided with the PICDEM 2 demonstration board on a PRO MATE II device programmer, or a PICSTART Plus development programmer, and easily test firmware. The MPLAB ICE in-circuit emulator may also be used with the PICDEM 2 demonstration board to test firmware. A prototype area has been provided to the user for adding additional hardware and connecting it to the microcontroller socket(s). Some of the features include a RS-232 interface, push button switches, a potentiometer for simulated analog input, a serial EEPROM to demonstrate usage of the I^2C^{TM} bus and separate headers for connection to an LCD module and a keypad.

12.1 DC Characteristics: PIC16C54/55/56/57-RC, XT, 10, HS, LP (Commercial)

PIC16C54/55/56/57-RC, XT, 10, HS, LP (Commercial)			Standard Operating Conditions (unless otherwise specific Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial							
Param No.	Symbol	Characteristic/Device	Min	Тур†	Max	Units	Conditions			
D001	Vdd	Supply Voltage PIC16C5X-RC PIC16C5X-XT PIC16C5X-10 PIC16C5X-HS PIC16C5X-LP	3.0 3.0 4.5 4.5 2.5		6.25 6.25 5.5 5.5 6.25	V V V V				
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾	_	1.5*	_	V	Device in SLEEP Mode			
D003	VPOR	VDD Start Voltage to ensure Power-on Reset		Vss	—	V	See Section 5.1 for details on Power-on Reset			
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*		—	V/ms	See Section 5.1 for details on Power-on Reset			
D010	IDD	Supply Current ⁽²⁾ PIC16C5X-RC ⁽³⁾ PIC16C5X-XT PIC16C5X-10 PIC16C5X-HS PIC16C5X-HS PIC16C5X-LP	 	1.8 1.8 4.8 4.8 9.0 15	3.3 3.3 10 10 20 32	mA mA mA mA μA	Fosc = 4 MHz, VDD = $5.5V$ Fosc = 4 MHz, VDD = $5.5V$ Fosc = 10 MHz, VDD = $5.5V$ Fosc = 10 MHz, VDD = $5.5V$ Fosc = 20 MHz, VDD = $5.5V$ Fosc = 32 kHz, VDD = $3.0V$, WDT disabled			
D020	Ipd	Power-down Current ⁽²⁾	_	4.0 0.6	12 9	μΑ μΑ	VDD = 3.0V, WDT enabled VDD = 3.0V, WDT disabled			

* These parameters are characterized but not tested.

† Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.

- a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/disabled as specified.
- b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
- **3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k Ω .

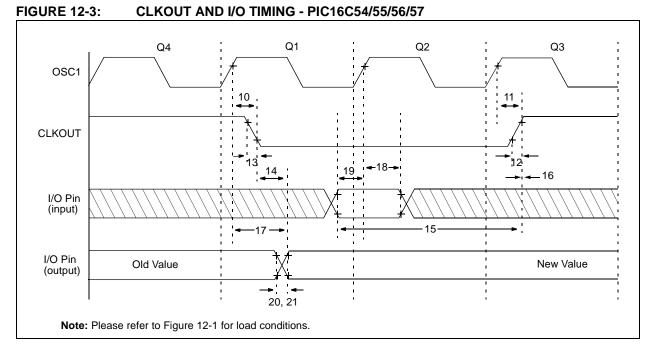


TABLE 12-2: CLKOUT AND I/O TIMING REQUIREMENTS - PIC16C54/55/56/57

AC Char	acteristics	$-40^{\circ}C \le TA \le -40^{\circ}C \le -40^{\circ$	ss otherwise specified) = +70°C for commercial = +85°C for industrial = +125°C for extended					
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units		
10	TosH2ckL	OSC1↑ to CLKOUT↓ ⁽¹⁾	_	15	30**	ns		
11	TosH2ckH	OSC1↑ to CLKOUT↑ ⁽¹⁾	_	15	30**	ns		
12	TckR	CLKOUT rise time ⁽¹⁾		5.0	15**	ns		
13	TckF	CLKOUT fall time ⁽¹⁾	—	5.0	15**	ns		
14	TckL2ioV	CLKOUT↓ to Port out valid ⁽¹⁾			40**	ns		
15	TioV2ckH	Port in valid before CLKOUT ⁽¹⁾	0.25 TCY+30*	_	_	ns		
16	TckH2iol	Port in hold after CLKOUT ⁽¹⁾	0*	_	_	ns		
17	TosH2ioV	OSC1↑ (Q1 cycle) to Port out valid ⁽²⁾	_		100*	ns		
18	TosH2iol	OSC1 [↑] (Q2 cycle) to Port input invalid (I/O in hold time)	TBD	—		ns		
19	TioV2osH	Port input valid to OSC1↑ (I/O in setup time)	TBD	—	—	ns		
20	TioR	Port output rise time ⁽²⁾	—	10	25**	ns		
21	TioF	Port output fall time ⁽²⁾	—	10	25**	ns		

* These parameters are characterized but not tested.

** These parameters are design targets and are not tested. No characterization data available at this time.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

Note 1: Measurements are taken in RC Mode where CLKOUT output is 4 x Tosc.

2: Please refer to Figure 12-1 for load conditions.

FIGURE 12-5: TIMER0 CLOCK TIMINGS - PIC16C54/55/56/57

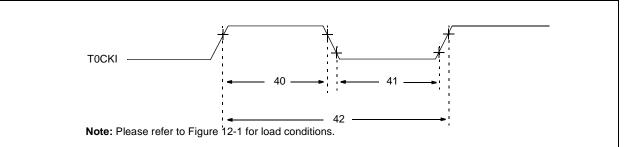


TABLE 12-4: TIMER0 CLOCK REQUIREMENTS - PIC16C54/55/56/57

AC Ch	AC CharacteristicsStandard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended							
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions	
40	Tt0H	T0CKI High Pulse Width - No Prescaler - With Prescaler	0.5 Tcy + 20* 10*		_	ns ns		
41	Tt0L	T0CKI Low Pulse Width - No Prescaler - With Prescaler	0.5 Tcy + 20* 10*		_	ns ns		
42	Tt0P	T0CKI Period	20 or <u>Tcy + 40</u> * N			ns	Whichever is greater. N = Prescale Value (1, 2, 4,, 256)	

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

AC Char	acteristics	$\begin{array}{llllllllllllllllllllllllllllllllllll$									
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions				
1	Tosc	External CLKIN Period ⁽¹⁾	250	_	_	ns	XT osc mode				
			250	—	—	ns	HS osc mode (04)				
			100	—		ns	HS osc mode (10)				
			50	—		ns	HS osc mode (20)				
			5.0	_	—	μS	LP OSC mode				
		Oscillator Period ⁽¹⁾	250		_	ns	RC OSC mode				
			250	—	10,000	ns	XT OSC mode				
			250	—	250	ns	HS OSC mode (04)				
			100	—	250	ns	HS osc mode (10)				
			50	—	250	ns	HS osc mode (20)				
			5.0	_	200	μS	LP OSC mode				
2	Тсу	Instruction Cycle Time ⁽²⁾	—	4/Fosc		_					
3	TosL, TosH	Clock in (OSC1) Low or High	50*		_	ns	XT oscillator				
		Time	20*	—	—	ns	HS oscillator				
			2.0*	_	—	μS	LP oscillator				
4	TosR, TosF	Clock in (OSC1) Rise or Fall	_	—	25*	ns	XT oscillator				
		Time	—	—	25*	ns	HS oscillator				
			_	—	50*	ns	LP oscillator				

TABLE 13-1:	EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16CR54A
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These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.

Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

when an external clock input is used, the "max" cycle time limit is "Du" (no clock) for all device

2: Instruction cycle period (TcY) equals four times the input oscillator time base period.



FIGURE 13-4: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16CR54A

TABLE 13-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16CR54A

AC Chara	cteristics	Standard Operating Conditions (uOperating Temperature $0^{\circ}C \leq$ $-40^{\circ}C \leq$ $-40^{\circ}C \leq$	TA ≤ +7 TA ≤ +8	0°C for 5°C for	comme industria	rcial al	
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions
30	TmcL	MCLR Pulse Width (low)	1.0*			μS	VDD = 5.0V
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	7.0*	18*	40*	ms	VDD = 5.0V (Comm)
32	Tdrt	Device Reset Timer Period	7.0*	18*	30*	ms	VDD = 5.0V (Comm)
34	Tioz	I/O Hi-impedance from MCLR Low	_	_	1.0*	μS	

These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5.0V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.



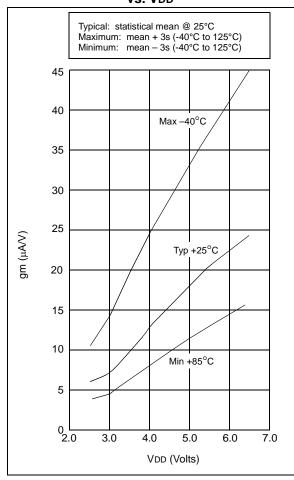
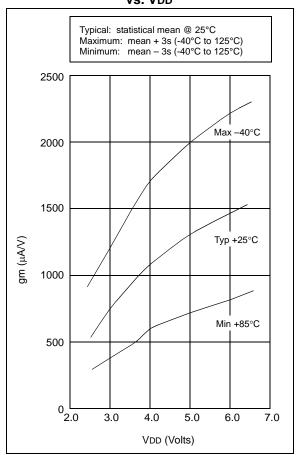


FIGURE 14-18:

TRANSCONDUCTANCE (gm) OF XT OSCILLATOR vs. VDD



15.1 DC Characteristics: PIC16C54A-04, 10, 20 (Commercial) PIC16C54A-04I, 10I, 20I (Industrial) PIC16LC54A-04 (Commercial) PIC16LC54A-04I (Industrial)

PIC16L0	PIC16LC54A-04Standard Operating Conditions (unless otherwise specified Operating TemperaturePIC16LC54A-04I (Commercial, Industrial) $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial							
PIC16C	54A-04, 10 54A-04, 10 54A-04I, 1 hercial, Ind), 20 01, 201	$\begin{array}{c} \mbox{Standard Operating Conditions (unless otherwise specified operating Temperature} & 0^{\circ}C \leq TA \leq +70^{\circ}C \mbox{ for commercial} \\ -40^{\circ}C \leq TA \leq +85^{\circ}C \mbox{ for industrial} \end{array}$					
Param No.	Symbol	Characteristic/Device	Min Typ† Max Units Conditions					
	Vdd	Supply Voltage			•			
D001		PIC16LC54A	3.0 2.5	_	6.25 6.25	V V	XT and RC modes LP mode	
D001A		PIC16C54A	3.0 4.5	_	6.25 5.5	V V	RC, XT and LP modes HS mode	
D002	Vdr	RAM Data Retention Voltage ⁽¹⁾	—	1.5*	—	V	Device in SLEEP mode	
D003	VPOR	VDD Start Voltage to ensure Power-on Reset	—	Vss	—	V	See Section 5.1 for details on Power-on Reset	
D004	SVDD	VDD Rise Rate to ensure Power-on Reset	0.05*	—	—	V/ms	See Section 5.1 for details on Power-on Reset	
	IDD	Supply Current ⁽²⁾						
D005		PIC16LC5X	—	0.5	2.5	mA	Fosc = 4.0 MHz, VDD = 5.5V, RC ⁽³⁾ and XT modes	
			—	11	27	μA	Fosc = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Commercial	
			—	11	35	μA	Fosc = 32 kHz, VDD = 2.5V, WDT disabled, LP mode, Industrial	
D005A		PIC16C5X	—	1.8	2.4	mA	Fosc = 4.0 MHz, VDD = 5.5V, RC ⁽³⁾ and XT modes	
			—	2.4	8.0	mA	Fosc = 10 MHz, VDD = 5.5V, HS mode	
			_	4.5 14	16 29	mA μA	Fosc = 20 MHz, VDD = 5.5V, HS mode Fosc = 32 kHz, VDD = 3.0V, WDT disabled, LP mode, Commercial	
			—	17	37	μA	Fosc = 32 kHz , VDD = 3.0V , WDT disabled, LP mode, Industrial	

Legend: Rows with standard voltage device data only are shaded for improved readability.

These parameters are characterized but not tested.

- † Data in "Typ" column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
- **Note 1:** This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - 3: Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k Ω .

15.2 DC Characteristics: PIC16

PIC16C54A-04E, 10E, 20E (Extended) PIC16LC54A-04E (Extended)

PIC16LC54A-04E (Extended)							tions (unless otherwise specified) $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended
PIC16C54A-04E, 10E, 20E (Extended)				ard Ope ting Terr	-		tions (unless otherwise specified) $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended
Param No. Symbol Characteristic				Тур†	Max	Units	Conditions
	IPD	Power-down Current ⁽²⁾					
D020		PIC16LC54A	_	2.5 0.25	15 7.0	μΑ μΑ	VDD = 2.5V, WDT enabled, Extended VDD = 2.5V, WDT disabled, Extended
D020A		PIC16C54A		5.0 0.8	22 18*	μΑ μΑ	VDD = 3.5V, WDT enabled VDD = 3.5V, WDT disabled

Legend: Rows with standard voltage device data only are shaded for improved readability.

* These parameters are characterized but not tested.

- † Data in the Typical ("Typ") column is based on characterization results at 25°C. This data is for design guidance only and is not tested.
- **Note 1:** This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.
 - 2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as bus loading, oscillator type, bus rate, internal code execution pattern and temperature also have an impact on the current consumption.
 - a) The test conditions for all IDD measurements in active Operation mode are: OSC1 = external square wave, from rail-to-rail; all I/O pins tristated, pulled to Vss, T0CKI = VDD, MCLR = VDD; WDT enabled/ disabled as specified.
 - b) For standby current measurements, the conditions are the same, except that the device is in SLEEP mode. The power-down current in SLEEP mode does not depend on the oscillator type.
 - **3:** Does not include current through REXT. The current through the resistor can be estimated by the formula: IR = VDD/2REXT (mA) with REXT in k Ω .

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FIGURE 17-9: TIMER0 CLOCK TIMINGS - PIC16C5X, PIC16CR5X

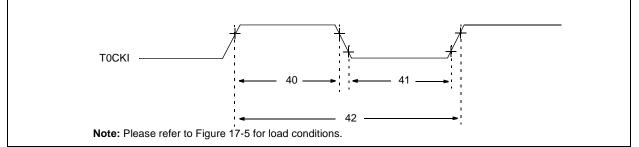


TABLE 17-4: TIMER0 CLOCK REQUIREMENTS - PIC16C5X, PIC16CR5X

ļ	AC CharacteristicsStandard Operating Conditions (unless otherwise specified) Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial $-40^{\circ}C \le TA \le +85^{\circ}C$ for industrial $-40^{\circ}C \le TA \le +125^{\circ}C$ for extended								
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions		
40	Tt0H	T0CKI High Pulse Width - No Prescaler	0.5 Tcy + 20*	_	_	ns			
		- With Prescaler	10*	—	—	ns			
41	TtOL	T0CKI Low Pulse Width - No Prescaler	0.5 Tcy + 20*	_	_	ns			
		- With Prescaler	10*	—	_	ns			
42	Tt0P	T0CKI Period	20 or <u>Tcy + 40</u> * N			ns	Whichever is greater. N = Prescale Value (1, 2, 4,, 256)		

These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

18.0 DEVICE CHARACTERIZATION - PIC16LC54A

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean - 3σ) respectively, where σ is a standard deviation, over the whole temperature range.

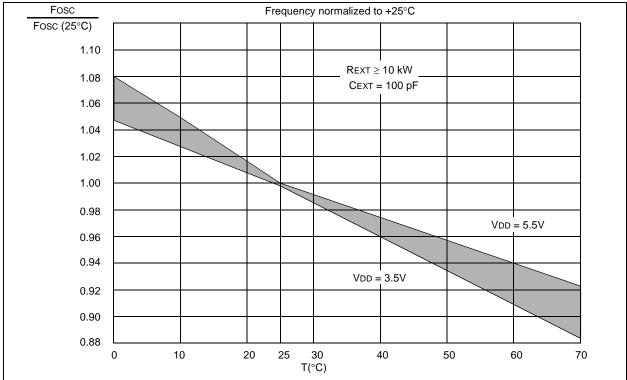


FIGURE 18-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

TABLE 18-1: RC OSCILLATOR FREQUENCIES

Сехт	Rext	Average Fosc @ 5V, 25°C				
20 pF	3.3K	5 MHz	± 27%			
	5K	3.8 MHz	± 21%			
	10K	2.2 MHz	± 21%			
	100K	262 kHz	± 31%			
100 pF	3.3K	1.63 MHz	± 13%			
	5K	1.2 MHz	± 13%			
	10K	684 kHz	± 18%			
	100K	71 kHz	± 25%			
300 pF	3.3K	660 kHz	± 10%			
	5.0K	484 kHz	± 14%			
	10K	267 kHz	± 15%			
	100K	29 kHz	± 19%			

The frequencies are measured on DIP packages.

The percentage variation indicated here is part-to-part variation due to normal process distribution. The variation indicated is ± 3 standard deviation from average value for VDD = 5V.

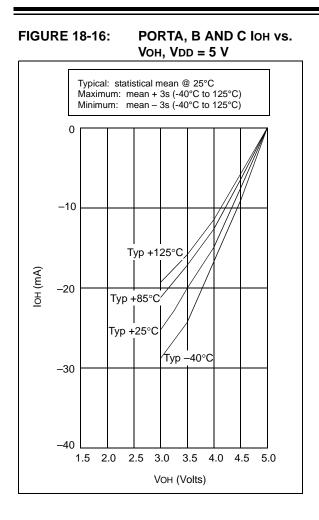
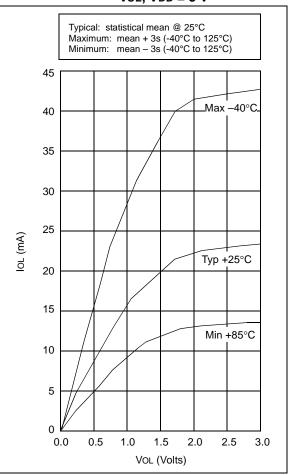


FIGURE 18-17: PORTA, B AND C IOL vs. Vol, VDD = 3 V



19.4 **Timing Diagrams and Specifications**

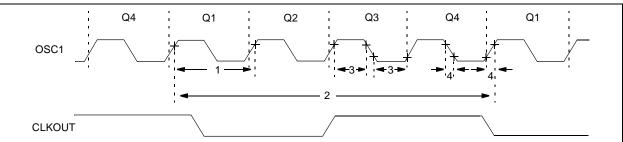


FIGURE 19-3: EXTERNAL CLOCK TIMING - PIC16C5X-40

EXTERNAL CLOCK TIMING REQUIREMENTS - PIC16C5X-40 TABLE 19-1:

AC Chara	cteristics	Standard Operating Conditions (unless otherwise specified)Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ for commercial						
Param No.	Symbol	Characteristic		Тур†	Max	Units	Conditions	
	Fosc	External CLKIN Frequency ⁽¹⁾	20	_	40	MHz	HS osc mode	
1	Tosc	External CLKIN Period ⁽¹⁾	25	_	_	ns	HS OSC mode	
2	Тсу	Instruction Cycle Time ⁽²⁾	—	4/Fosc	_	—		
3	TosL, TosH	Clock in (OSC1) Low or High Time	6.0*	_	_	ns	HS oscillator	
4	TosR, TosF	Clock in (OSC1) Rise or Fall Time	—	_	6.5*	ns	HS oscillator	

- * These parameters are characterized but not tested.
- † Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.
- Note 1: All specified values are based on characterization data for that particular oscillator type under standard operating conditions with the device executing code. Exceeding these specified limits may result in an unstable oscillator operation and/or higher than expected current consumption. When an external clock input is used, the "max" cycle time limit is "DC" (no clock) for all devices.

 - 2: Instruction cycle period (TCY) equals four times the input oscillator time base period.



FIGURE 19-5: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER TIMING - PIC16C5X-40

TABLE 19-3: RESET, WATCHDOG TIMER, AND DEVICE RESET TIMER - PIC16C5X-40

AC Charac	teristics	Standard Operating Conditions (unless otherwise specified)Operating Temperature $0^{\circ}C \le TA \le +70^{\circ}C$ (commercial)Operating Voltage VDD range is described in Section 19.1.						
Param No.	Symbol	Characteristic	Min	Тур†	Max	Units	Conditions	
30	TmcL	MCLR Pulse Width (low)	1000*	_	_	ns	VDD = 5.0V	
31	Twdt	Watchdog Timer Time-out Period (No Prescaler)	9.0*	18*	30*	ms	VDD = 5.0V (Comm)	
32	Tdrt	Device Reset Timer Period	9.0*	18*	30*	ms	VDD = 5.0V (Comm)	
34	Tioz	I/O Hi-impedance from MCLR Low	100*	300*	1000*	ns		

* These parameters are characterized but not tested.

† Data in the Typical ("Typ") column is at 5V, 25°C unless otherwise stated. These parameters are for design guidance only and are not tested.

20.0 DEVICE CHARACTERIZATION - PIC16LC54C 40MHz

The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only. The performance characteristics listed herein are not tested or guaranteed. In some graphs or tables, the data presented may be outside the specified operating range (e.g., outside specified power supply range) and therefore outside the warranted range.

"Typical" represents the mean of the distribution at 25°C. "Maximum" or "minimum" represents (mean + 3σ) or (mean - 3σ) respectively, where σ is a standard deviation, over the whole temperature range.





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28-Lead Skinny Plastic Dual In-line (SP) - 300 mil (PDIP)





в

	Units	s INCHES*			MILLIMETERS		
Dimension Limits		MIN	NOM	MAX	MIN	NOM	MAX
Number of Pins	n		28			28	
Pitch	р		.100			2.54	
Top to Seating Plane	А	.140	.150	.160	3.56	3.81	4.06
Molded Package Thickness	A2	.125	.130	.135	3.18	3.30	3.43
Base to Seating Plane	A1	.015			0.38		
Shoulder to Shoulder Width	E	.300	.310	.325	7.62	7.87	8.26
Molded Package Width	E1	.275	.285	.295	6.99	7.24	7.49
Overall Length	D	1.345	1.365	1.385	34.16	34.67	35.18
Tip to Seating Plane	L	.125	.130	.135	3.18	3.30	3.43
Lead Thickness	С	.008	.012	.015	0.20	0.29	0.38
Upper Lead Width	B1	.040	.053	.065	1.02	1.33	1.65
Lower Lead Width	В	.016	.019	.022	0.41	0.48	0.56
Overall Row Spacing	èB	.320	.350	.430	8.13	8.89	10.92
Mold Draft Angle Top	α	5	10	15	5	10	15
Mold Draft Angle Bottom	β	5	10	15	5	10	15

* Controlling Parameter § Significant Characteristic

eВ

Dimension D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed

.010" (0.254mm) per side.

JEDEC Equivalent: MO-095

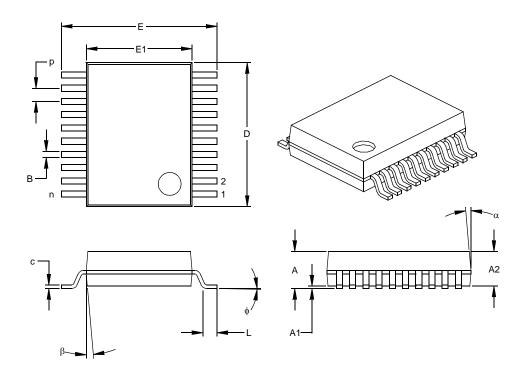
Drawing No. C04-070

- p -

Notes:

20-Lead Plastic Shrink Small Outline (SS) - 209 mil, 5.30 mm (SSOP)

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	Units	INCHES*			MILLIMETERS			
Dimensio	MIN	NOM	MAX	MIN	NOM	MAX		
Number of Pins	n		20			20		
Pitch	р		.026			0.65		
Overall Height	Α	.068	.073	.078	1.73	1.85	1.98	
Molded Package Thickness	A2	.064	.068	.072	1.63	1.73	1.83	
Standoff §	A1	.002	.006	.010	0.05	0.15	0.25	
Overall Width	Е	.299	.309	.322	7.59	7.85	8.18	
Molded Package Width	E1	.201	.207	.212	5.11	5.25	5.38	
Overall Length	D	.278	.284	.289	7.06	7.20	7.34	
Foot Length	L	.022	.030	.037	0.56	0.75	0.94	
Lead Thickness	С	.004	.007	.010	0.10	0.18	0.25	
Foot Angle	ф	0	4	8	0.00	101.60	203.20	
Lead Width	В	.010	.013	.015	0.25	0.32	0.38	
Mold Draft Angle Top	α	0	5	10	0	5	10	
Mold Draft Angle Bottom	β	0	5	10	0	5	10	

* Controlling Parameter

§ Significant Characteristic

Notes:

Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed .010" (0.254mm) per side. JEDEC Equivalent: MO-150 Drawing No. C04-072